

Product Change Notification / CAAN-21CAKH543

Date:

23-Jun-2023

Product Category:

Power Discrete Components

PCN Type:

Manufacturing Change

Notification Subject:

CCB 6198 Initial Notice: Qualification Microchip Technology Colorado – Fab 5 (MCSO) as an additional fabrication site for selected 700V, 1200V and 1700V SiC MOSFET products of MSC0xxSMAxx070xx, MSC0xxSMAxx120xx, MSC0xxSMAxx170xx, MSC180SMA120B, MSC360SMA120B and MSC750SMA170xx device families available in die sales products and 3L/4L TO-247 package.

Affected CPNs:

CAAN-21CAKH543_Affected_CPN_06232023.pdf CAAN-21CAKH543_Affected_CPN_06232023.csv

Notification Text:

PCN Status:Initial Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification Microchip Technology Colorado – Fab 5 (MCSO) as an additional fabrication site for selected 700V, 1200V and 1700V SiC MOSFET products of MSC0xxSMAxx070xx, MSC0xxSMAxx120xx, MSC0xxSMAxx170xx, MSC180SMA120B, MSC360SMA120B and MSC750SMA170xx device families available in die sales products and 3L/4L TO-247 product.

Pre and Post Change Summary:

		Pre Change	Post	Change	
Fabrica	ion Site	X-Fab Silicon Foundries (XFTX)	X-Fab Silicon Foundries (XFTX)	Microchip Technology Colorado – Fab 5 (MCSO)	
Certifi	cation	ISO 9001	ISO 9001	IATF16949	
	laterial (Cu	Cu	Cu	
Molding	Molding For 3L	MG15F-35A	MG15F-35A	G780C	
Compound Material	For 4L	MG15F-0140	MG15F-0140	G780C	
Die Attach For 3L		1-03-0068-0009	1-03-0068-0009	1-06-9999-0001 (Wire)	
Material	For 4L	1-06-9999-0001	1-06-9999-0001	1-06-9999-0001 (Wire)	

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve productivity and on-time delivery performance by qualifying MCSO as an additional fabrication site.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:November 2023

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	June 2023						November 2023				3
Workweek	2	2	2	2	2		4	4	4	4	4
	2	3	4	5	6		4	5	6	7	8
Initial PCN Issue				Х							
Date Ougl Papart											
Qual Report Availability											Х
Final PCN Issue									·		Χ

Date													
Nethod to Identify	Change:	Trace	abilit	y cod	le								
Qualification Plan:	lease op	en th	e atta	ıchm	ents	incl	uded	l with	n this	PCN	labe	eled as PCN_#_Qual_Plan.	
Revision History :Ju	ne 23, 20	23: Is	sued	initia	ıl not	ifica	ation						
The change describ material content of						Mic	rochi	p's c	urrei	nt reg	ulat	ory compliance regarding the	
Attachments:													
PCN_CAAN-21CA	KH543 ₋	.Qual	ifica	tion	Plan	ı.pd	lf						
Please contact you		Micro	chip	sale	es off	fice	with	n que	estio	ns oi	- cor	ncerns regarding this notification	l .
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Affected Catalog Part Numbers (CPN)

MSC035SMA070B

MSC035SMA070B4

MSC035SMA170B

MSC035SMA170B4

MSC040SMA120B

MSC040SMA120B4

MSC060SMA070B

MSC060SMA070B4

MSC080SMA120B

MSC080SMA120B4

MSC090SMA070B

MSC180SMA120B

MSC360SMA120B

MSC750SMA170B

MSC750SMA170B4

Date: Thursday, June 22, 2023



QUALIFICATION PLAN SUMMARY

PCN #: CAAN-21CAKH543

Date: March 11, 2023

Qualification Microchip Technology Colorado – Fab 5 (MCSO) as an additional fabrication site for selected 700V, 1200V and 1700V SiC MOSFET products of MSC0xxSMAxx070xx, MSC0xxSMAxx120xx, MSC0xxSMAxx170xx, MSC180SMA120B, MSC360SMA120B and MSC750SMA170xx device families available in die sales products and 3L/4L TO-247 package.

Purpose: Qualification Microchip Technology Colorado – Fab 5 (MCSO) as an additional fabrication site for selected 700V, 1200V and 1700V SiC MOSFET products of MSC0xxSMAxx070xx, MSC0xxSMAxx120xx, MSC0xxSMAxx170xx, MSC180SMA120B, MSC360SMA120B and MSC750SMA170xx device families available in die sales products and 3L/4L TO-247 package.

CCB No.: 6198

Package:	
Type:	3L TO-247 and 4L TO-247
Width or Size:	12 mm x 14 mm
Leadframe:	
Part Number:	1-01-0011-0009 (3L) 1-01-0011-0010 (4L)
Paddle Size:	0.74168 cm x 1.25 cm
Material:	Cu
Pad Plating:	Bare Cu
Process:	Stamped
Lead-lock (Y/N):	Groove
Lead Finish:	Matte Tin
LF Thickness:	0.4953 cm
Wire:	
Material:	99.99% Aluminum
Die Attach Epoxy:	
Part Number	1-06-9999-0001
Conductive:	Yes
Mold Compound:	G780C
Reliability Test plan:	Q101 Rev E Reliability Test plan:

Test Group A: Accelerated Environment Stress Tests

Test	Stress Name	Spec Reference	Conditions	Devices Per Lot	Read Points/Notes
A2	HAST [Highly Accelerated Stress Test]	JESD22-A-110	Time: 96 Hours Ta: 130 °C, Rhumidity: 85%, P: 33.3 PSIA Vds: 42 V DC ET must Occur within 96 Hours	3x80	DC ET at: Pre and Post
А3	UHAST [Unbiased HAST]	JESD22-A-102	Time: 96 Hours Ta: 130 °C Rhumidity: 85% P: 33.3 PSIA DC ET must Occur within 96 Hours	3x80	DC ET at: Pre and Post
A4	TC [Temperature Cycle]	JESD22-A-104 Appendix Six	Number of Cycles: 400 Ta Range: -55°C to 175°C Ramp: 16°C/Min	3x80	DC ET at: Pre and Post
A4a	TCHT [Temperature Cycling Hot Test	JESD22-A-104 Appendix Six J-STD-035	125°C Test after TC followed by de-cap Wire pull on all wires from five devices	3x80	
A5	IOL [Intermittent Operational Life]	MIL-STD-750 Method 1037.2	Number of Cycles: 4650 Duty Cycle: 180 s Powered, 210 s Cooling ΔTj: 125°C DC ET must Occur within 96 Hours	3x80	DC ET at: Pre and Post

Test Group B: Accelerated lifetime Simulation Tests

Test	Stress Name	Spec Reference	Conditions	Devices Per Lot	Read Points/Notes
B1	HTRB [High Temp Reverse Bias]	MIL-STD-750-1 M1039.4 2.2.1 Condition A	Vds: 100% Rated Tj: 175°C Duration: 1000 hours Bias must be maintained until Ta is 35°C DC ET must occur within 24 hours of bias removal	3x84	DC ET at: • Pre • 1000 Hours

Test Group C: Package Assembly Integrity Tests

Test	Stress Name	Spec Reference	Conditions	Devices Per Lot	Read Points/Notes
C1	DPA [Destructive Physical Analysis]	AEC-Q101-004 Section Four	Random sample of parts that have successfully completed HAST, and TC		2 Per Stress Per package
C2	PD [Physical Dimensions]	JESD22-B-100		30 per package	All parts from stresses
СЗ	WBPS [Wire Bond Pull Strength]	MIL-STD-750 Method 2037	Condition C or D	10 Bonds, from a min of 5 parts	One Lot Per Package
C4	WBSS [Wire Bond Shear Strength]	AEC Q101-003 JESD22 B116		10 Bonds, from a min of 5 parts	One Lot Per Package
C5	DS [Die Shear]	MIL-STD-750 Method 2017		5 Per Package	One Lot Per Subcon
C6	TS [Terminal Strength]	MIL-STD-750-2 Method 2037	Evaluate lead integrity of through-hole leaded parts only.	30 per package	One Lot Per Subcon
C8	RSH [Resistance to Solder Heat]	JESD22-A-11 JESD22-B-106			
C9	TR [Thermal Resistance]	JESD24-3 JESD24-4 JESD24-6	Pre/Post Process Change	10	One Lot Per Subcon per package
C10	SD [Solderability]	STD-002 JESD22-B-102	Magnification 50X Method A for through-hole Method B and D For SMD	10	One Lot Per Subcon per package
C11	WG [Whisker Growth Evaluation]	AEC-Q005	For whisker requirements. Test to be done on a family basis		Already Completed by Fastech

Device Reliability: Additional Parametric shift Requirements

- Parts not remaining within ± 20% of the initial reading of each test after completion of environmental testing. For leakages below 100nA, tester accuracy may prevent a post stress analysis to initial reading.
- For IOL, PTC and TC tests on products with RDSon ≤ 2.5 mOhm max, the allowed value for the shift of RDSon is ≤ 0.5 mOhm.
- For breakdown voltage only, a shift of >20% of the initial measured value is a failure only if the final reading is within 20% of the datasheet maximum value.
- The allowed leakage limits which are not to exceed 10 times the initial value for moisture tests and 5 times the initial value for all others.
- For MOSFETs only, for 0h test values <10nA (IGSS and IDSS), the allowed value after stressing is 100nA for moisture tests and 50nA for other tests.

Primary Qual Stress Allocation

MSL and Voltage	Part Number	Lot Number	IOL	тс	HAST	UHAST
	MSC035SMA170 Lot 1	SC2311	80	80	80	80
MSL: 3681 1700 V	MSC035SMA170 Lot 2	SC2331	80	80	80	80
	MSC035SMA170 Lot 3	SC2332	80	80	80	80